

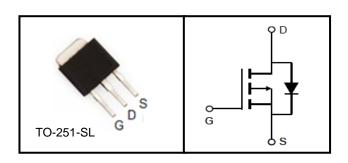
# **100V P-Channel Trench MOSFET**

#### **FEATURES**

- Trench Power MOSFET Technology
- Low R<sub>DS(ON)</sub>
- Low Gate Charge
- Optimized For Fast-switching Applications

#### **APPLICATIONS**

- Load Switches
- Battery Switch





Device Marking and Package Information			
Device	Package	Marking	
TTE01P10AT	TO-251-SL	01P10AT	

<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted				
Parameter	Symbol	Value	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	-100	V	
Continuous Drain Current	I <sub>D</sub>	-1.5	А	
Pulsed Drain Current (note1)	I <sub>DM</sub>	-6	А	
Gate-Source Voltage	V <sub>GSS</sub>	±20	V	
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	0.8	mJ	
Avalanche Current (note1)	I <sub>AR</sub>	-2	А	
Power Dissipation ( $T_C = 25^{\circ}C$ )	$P_{D}$	1.5	W	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+175	°C	

Thermal Resistance				
Parameter	Symbol	Value	Unit	
Thermal Resistance, Junction-to-Case	uioc I		12001	
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	60	K/W	



<b>Specifications</b> $T_J = 25^{\circ}C$ , ur	less othe	rwise noted				
Parameter	Symbol	Test Conditions	Value			Unit
		rost containons	Min.	Тур.	Max.	Oilit
Static				_		
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = -250\mu A$	-100			V
Zoro Coto Voltago Droin Current	I <sub>DSS</sub>	$V_{DS} = -100V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			-1	μA
Zero Gate Voltage Drain Current		$V_{DS} = -100V, V_{GS} = 0V, T_{J} = 150^{\circ}C$			-100	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 20V$			±100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-1.0		-3.0	V
Drain Course On Registeres (Note2)	D	V <sub>GS</sub> = -10V, I <sub>D</sub> = -1A		1.29	1.54	Ω
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -1A		1.43	1.66	Ω
Forward Transconductance (Note3)	$g_{fs}$	$V_{DS} = -3V, I_{D} = -1.5A$		0.3		S
Dynamic						
Input Capacitance	C <sub>iss</sub>	V - 0V		210		
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = -25V,$		17		pF
Reverse Transfer Capacitance	$C_{rss}$	f = 1.0MHz		5		
Total Gate Charge	$Q_g$			25		nC
Gate-Source Charge	$Q_{gs}$	$V_{DD} = -80V, I_{D} = -1A,$ $V_{GS} = -10V$		3		
Gate-Drain Charge	$Q_{gd}$			7		
Turn-on Delay Time	t <sub>d(on)</sub>			8		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = -100V, I_{D} = -1A,$		4		
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 2.5\Omega$		32		ns
Turn-off Fall Time	t <sub>f</sub>			7		
Drain-Source Body Diode Characteris	stics					
Continuous Body Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25°C			-1	Δ.
Pulsed Diode Forward Current	I <sub>SM</sub>				-4	Α
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}C$ , $I_{SD} = -1A$ , $V_{GS} = 0V$			-1.2	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = -1A,		25		ns
Reverse Recovery Charge	Q <sub>rr</sub>	di <sub>F</sub> /dt = 100A/μs		31		nC

### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2.  $I_{AS}$  = -2A,  $V_{DD}$  = 50V,  $R_{G}$  = 25 $\Omega$ , Starting  $T_{J}$  = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%



# **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

Figure 1. Output Characteristics

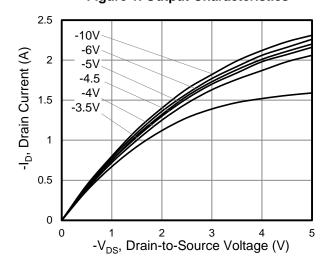
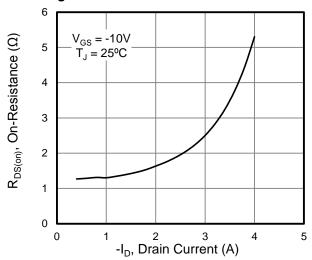


Figure 3. On-Resistance vs. Drain Current



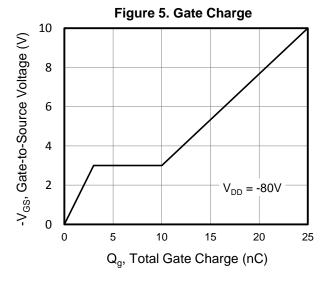


Figure 2. Transfer Characteristics

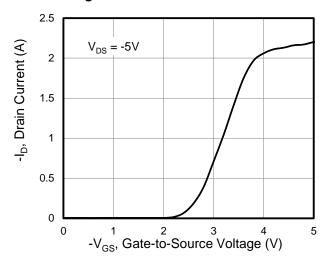


Figure 4. Capacitance

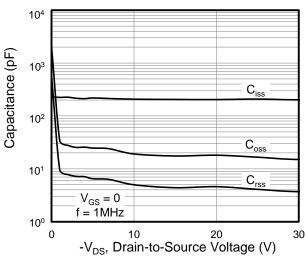
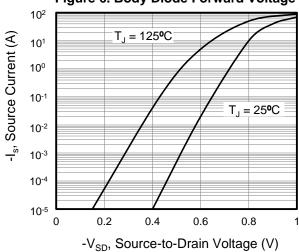


Figure 6. Body Diode Forward Voltage







# **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

Figure 7. On-Resistance vs.

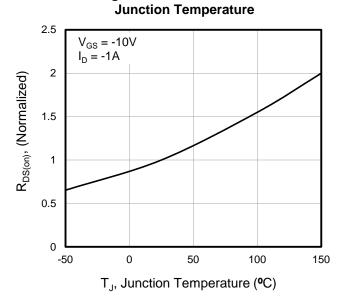


Figure 8. Threshold Voltage vs. Junction Temperature

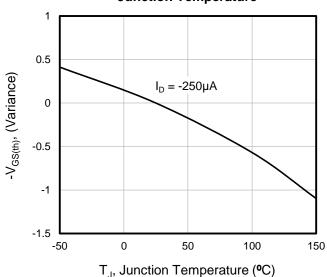


Figure 9. Transient Thermal Impedance

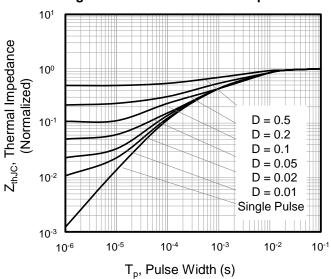


Figure A: Gate Charge Test Circuit and Waveform

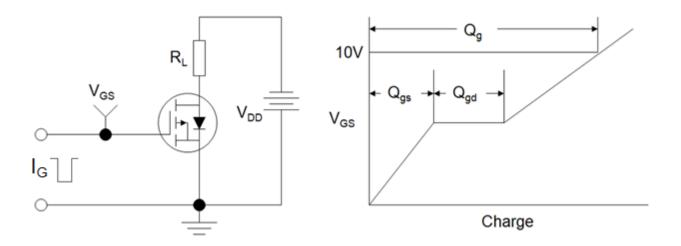


Figure B: Resistive Switching Test Circuit and Waveform

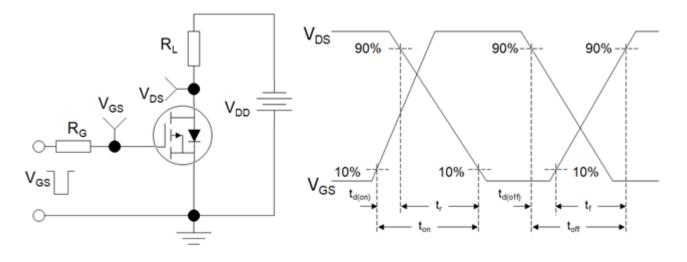
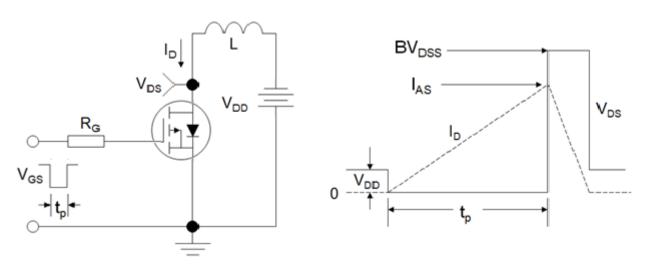
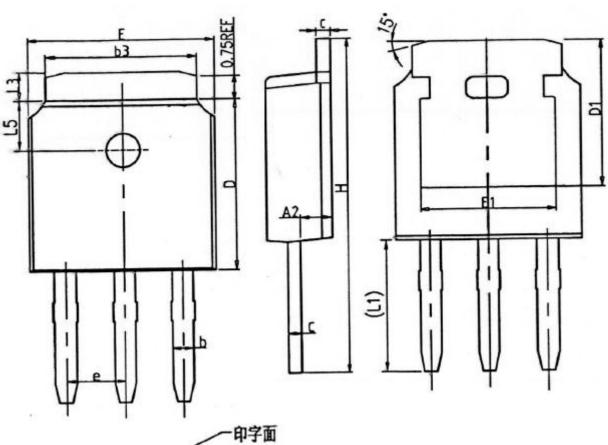


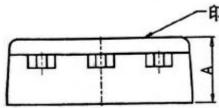
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





TO-251-SL





Unit: mm			
Symbol	Min.	Max.	
Α	2. 20	2. 40	
A2	0. 97	1. 17	
b	0. 68	0. 90	
b2	0.00	0.10	
b2′	0.00	0.10	
b3	5. 20	5. 50	
С	0. 43	0. 63	
D	5. 98	6. 22	

Unit: mm			
Symbol	Min. Max.		
D1	5. 30REF		
E	6. 40	6. 80	
E1	4. 63	-	
е	2. 286BSC		
Н	16. 22	16. 82	
L1	9. 15	9. 65	
L3	0.88	1. 28	
L5	1. 65	1. 95	



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